Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[TuE2] CMP Consumables: Conditioning, Monitoring, and Abrasives

Session Date	November 11 (Tue.), 2025
Session Time	14:50-16:30
Session Room	Room E (Sicily Room, 1F)
Session Chair	Dr. Hyunkyu Moon (KIMM, Korea)

[TuE2-1] [Invited] **14:50-15:20**

CMP Pad Conditioning of the Future: Fundamentals, Emerging Technologies, and Development Pathways

Yongsik Moon, Kyoung-Kuk Kwack, Joohan Lee, Jongkuk Park, Eunhwa Song, Youngtae Jeon, Juhee Lee, Sungyu Park, Yujeong Jin, and Jongjae Lee (EHWA Diamond, Korea)

[TuE2-2] [Invited] **15:20-15:50**

Slurry Sensing for CMP Processes

Jin Su Hong, Min Cheol Kim, and Min Ku Kim (Hanyang Univ., Korea)

[TuE2-3] [Invited] **15:50-16:10**

A Novel CMP Slurry Systems for Next-Generation Semiconductor Fabrication

Jongchul Shin and Sanghyun Ryu (Dongjin Semichem Co., Ltd., Korea)

[TuE2-4] [Invited] **16:10-16:30**

Post CMP Cleaning Strategies for Amorphous Silicon in Wafer Bonding Processes

Arunkumar G V, Wei-Tsu Tseng, Nancy Wang, and Donald Canaperi (IBM Research, USA)